

Product Change Notification - LIAL-17KNYR589

Date: 01 Feb 2018

Product Category: 32-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

Notification subject: CCB 3222 Initial Notice:Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC, 70nm SMIC and 200K wafer technologies available in 64L QFN packages.

Notification text:

PCN Status:
Initial notification.

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC, 70nm SMIC and 200K wafer technologies available in 64L QFN (9x9x 0.9mm) package.

Pre Change:

Assembled at MTAI assembly site

Post Change:

Assembled at MTAI or MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand Branch (MMT)
Wire material	Au	Au	
Die attach material	3280	3280	
Molding compound material	G700LTD	G700LTD	
Lead frame material	C194	C194	

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve on-time delivery performance by qualifying MMT as an additional assembly site

Reason for Change:
To improve on-time delivery performance by qualifying MMT as an additional assembly site

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2018					-->	April 2018			
Workweek	05	06	07	08	09		14	15	16	17
Initial PCN Issue Date	X									
Qual Report Availability									X	
Final PCN Issue Date									X	

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
February 01, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products

- Attachment(s):**
- [PCN_LIAL-17KNYR589_QUAL PLAN.pdf](#)
 - [PCN_LIAL-17KNYR589_AFFECTED CPN.pdf](#)
 - [PCN_LIAL-17KNYR589_AFFECTED CPN.xlsx](#)

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MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN#: LIAL-17KNYR589

Date

December 14, 2017

Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC, 70nm SMIC and 200K wafer technologies available in 64L QFN (9x9x0.9mm) package.

Purpose: Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 0.90nm TSMC, 70nm SMIC and 200K wafer technologies available in 64L QFN (9x9x0.9mm) package.

CCB No.: 3222

		Qualification Report
<u>Misc.</u>	Assembly site	MMT
	BD Number	BDM-001610/A
	MP Code (MPC)	WAAA17R4XDDL
	Part Number (CPN)	PIC32MZ1024ECG064-I/MR
<u>Lead-Frame</u>	Paddle size	311x311 mils
	Material	C194
	Surface	Bare Cu
	Treatment	BOT
	Process	Etched
	Lead-lock	No
	Part Number	10106408
Lead Plating	Matte Tin	
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	3280
	Conductive	Yes
<u>MC</u>	Part Number	G700LTD
<u>PKG</u>	PKG Type	QFN
	Pin/Ball Count	64
	PKG width/size	9x9x0.9mm
<u>Die</u>	Die Thickness	11 mils
	Die Size	217.7x228.9 mils
	Fab Process (site)	90nm TSMC

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002 ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MTAI	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Backward Solderability	J-STD-002 ; Perform 8 hours steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD. Mil. Std. 883-2011	22	5	1	27	> 95% lead coverage	5	MTAI	
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	15	0	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	15	0	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	MTAI	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
HTSL (High Temp Storage Life)	+175 C for 504 hours. Electrical test pre and post stress at +25°C and hot temp. 85°C. 1 lot to be tested at 85C	45	5	1	50	0	25	MTAI	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. 1 lot to be tested at 85C	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. 1 lot to be tested at 85C	77	5	3	246	0	15	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

PCN_LIAL-17KNYR589 CCB 3222 Initial Notice: Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um,90nm TSMC,70nm SMIC and 200K wafer technologies available in 64L QFN(9x9x 0.9mm)package

Affected Catalog Part Number

PCN_LIAL-17KNYR589
CATALOG_PART_NBR
DSPIC33EP128GM306-E/MR
DSPIC33EP128GM306-I/MR
DSPIC33EP128GM706-E/MR
DSPIC33EP128GM706-H/MR
DSPIC33EP128GM706-I/MR
DSPIC33EP128GM706T-I/MR
DSPIC33EP256GM306-E/MR
DSPIC33EP256GM306-I/MR
DSPIC33EP256GM706-E/MR
DSPIC33EP256GM706-I/MR
DSPIC33EP256MU806-E/MR
DSPIC33EP256MU806-I/MR
DSPIC33EP256MU806T-E/MR
DSPIC33EP256MU806T-I/MR
DSPIC33EP512GM306-E/MR
DSPIC33EP512GM306-I/MR
DSPIC33EP512GM706-E/MR
DSPIC33EP512GM706-I/MR
DSPIC33EP512GM706-I/MRC01
DSPIC33EP512GM706T-I/MRC01
DSPIC33EP512GP506-E/MR
DSPIC33EP512GP506-H/MR
DSPIC33EP512GP506-I/MR
DSPIC33EP512GP506T-E/MR
DSPIC33EP512GP506T-H/MR
DSPIC33EP512GP506T-I/MR
DSPIC33EP512GP806-E/MR
DSPIC33EP512GP806-I/MR
DSPIC33EP512GP806T-E/MR
DSPIC33EP512GP806T-I/MR
DSPIC33EP512MC206-E/MR
DSPIC33EP512MC206-H/MR
DSPIC33EP512MC206-I/MR
DSPIC33EP512MC206T-E/MR
DSPIC33EP512MC206T-H/MR
DSPIC33EP512MC206T-I/MR
DSPIC33EP512MC506-E/MR
DSPIC33EP512MC506-H/MR
DSPIC33EP512MC506-I/MR
DSPIC33EP512MC506T-E/MR
DSPIC33EP512MC506T-H/MR
DSPIC33EP512MC506T-I/MR
DSPIC33EP512MC806-E/MR
DSPIC33EP512MC806-I/MR

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CATALOG_PART_NBR
DSPIC33EP512MC806T-E/MR
DSPIC33EP512MC806T-I/MR
DSPIC33EV128GM006-E/MR
DSPIC33EV128GM006-H/MR
DSPIC33EV128GM006-I/MR
DSPIC33EV128GM006T-I/MR
DSPIC33EV128GM106-E/MR
DSPIC33EV128GM106-H/MR
DSPIC33EV128GM106-I/MR
DSPIC33EV128GM106T-I/MR
DSPIC33EV256GM006-E/MR
DSPIC33EV256GM006-H/MR
DSPIC33EV256GM006-I/MR
DSPIC33EV256GM006T-I/MR
DSPIC33EV256GM106-E/MR
DSPIC33EV256GM106-H/MR
DSPIC33EV256GM106-I/MR
DSPIC33EV256GM106T-I/MR
DSPIC33EV64GM006-E/MR
DSPIC33EV64GM006-H/MR
DSPIC33EV64GM006-I/MR
DSPIC33EV64GM006T-I/MR
DSPIC33EV64GM106-E/MR
DSPIC33EV64GM106-H/MR
DSPIC33EV64GM106-I/MR
DSPIC33EV64GM106T-I/MR
DSPIC33FJ128GP206A-E/MR
DSPIC33FJ128GP206A-I/MR
DSPIC33FJ128GP206AT-E/MR
DSPIC33FJ128GP206AT-I/MR
DSPIC33FJ128GP306A-E/MR
DSPIC33FJ128GP306A-I/MR
DSPIC33FJ128GP306AT-E/MR
DSPIC33FJ128GP306AT-I/MR
DSPIC33FJ128GP706A-E/MR
DSPIC33FJ128GP706A-H/MR
DSPIC33FJ128GP706A-I/MR
DSPIC33FJ128GP706AT-E/MR
DSPIC33FJ128GP706AT-H/MR
DSPIC33FJ128GP706AT-I/MR
DSPIC33FJ128MC506A-E/MR
DSPIC33FJ128MC506A-H/MR
DSPIC33FJ128MC506A-I/MR
DSPIC33FJ128MC506AT-E/MR

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DSPIC33FJ128MC506AT-H/MR
DSPIC33FJ128MC506AT-I/MR
DSPIC33FJ128MC706A-E/MR
DSPIC33FJ128MC706A-H/MR
DSPIC33FJ128MC706A-I/MR
DSPIC33FJ128MC706AT-E/MR
DSPIC33FJ128MC706AT-H/MR
DSPIC33FJ128MC706AT-I/MR
DSPIC33FJ256GP506A-E/MR
DSPIC33FJ256GP506A-I/MR
DSPIC33FJ256GP506AT-E/MR
DSPIC33FJ256GP506AT-I/MR
DSPIC33FJ32GS406-50I/MR
DSPIC33FJ32GS406-I/MR
DSPIC33FJ32GS406T-50I/MR
DSPIC33FJ32GS606-50I/MR
DSPIC33FJ32GS606-E/MR
DSPIC33FJ32GS606-I/MR
DSPIC33FJ32GS606T-50I/MR
DSPIC33FJ32GS606T-I/MRC01
DSPIC33FJ64GP206A-E/MR
DSPIC33FJ64GP206A-I/MR
DSPIC33FJ64GP206AT-E/MR
DSPIC33FJ64GP206AT-I/MR
DSPIC33FJ64GP306A-E/MR
DSPIC33FJ64GP306A-I/MR
DSPIC33FJ64GP306AT-E/MR
DSPIC33FJ64GP306AT-I/MR
DSPIC33FJ64GP706A-E/MR
DSPIC33FJ64GP706A-I/MR
DSPIC33FJ64GP706AT-E/MR
DSPIC33FJ64GP706AT-I/MR
DSPIC33FJ64GS406-50I/MR
DSPIC33FJ64GS406-E/MR
DSPIC33FJ64GS406-I/MR
DSPIC33FJ64GS406T-50I/MR
DSPIC33FJ64GS606-50I/MR
DSPIC33FJ64GS606-E/MR
DSPIC33FJ64GS606-I/MR
DSPIC33FJ64GS606T-50I/MR
DSPIC33FJ64MC506A-E/MR
DSPIC33FJ64MC506A-H/MR
DSPIC33FJ64MC506A-I/MR
DSPIC33FJ64MC506AT-E/MR

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PCN_LIAL-17KNYR589
CATALOG_PART_NBR
DSPIC33FJ64MC506AT-H/MR
DSPIC33FJ64MC506AT-I/MR
DSPIC33FJ64MC706A-E/MR
DSPIC33FJ64MC706A-I/MR
DSPIC33FJ64MC706AT-E/MR
DSPIC33FJ64MC706AT-I/MR
MRF24WB0/MR
MRF24WB0T/MR
MTCH62104-I/MR
MTCH62104T-I/MR
MTCH63105-I/MR
MTCH63105T-I/MR
PIC18F65K22-E/MR
PIC18F65K22-I/MR
PIC18F65K22T-E/MR
PIC18F65K22T-I/MR
PIC18F65K80-E/MR
PIC18F65K80-H/MR
PIC18F65K80-I/MR
PIC18F65K80T-I/MR
PIC18F65K90-E/MR
PIC18F65K90-I/MR
PIC18F65K90T-I/MR
PIC18F66K22-E/MR
PIC18F66K22-I/MR
PIC18F66K22T-E/MR
PIC18F66K22T-I/MR
PIC18F66K80-E/MR
PIC18F66K80-H/MR
PIC18F66K80-I/MR
PIC18F66K80T-I/MR
PIC18F66K90-E/MR
PIC18F66K90-I/MR
PIC18F66K90T-I/MR
PIC18F67K22-E/MR
PIC18F67K22-I/MR
PIC18F67K22-I/MRRSL
PIC18F67K22T-I/MR
PIC18F67K22T-I/MRRSL
PIC18F67K90-E/MR
PIC18F67K90-I/MR
PIC18F67K90-I/MRRSL
PIC18F67K90T-I/MR
PIC18LF65K80-I/MR

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CATALOG_PART_NBR
PIC18LF65K80T-I/MR
PIC18LF66K80-I/MR
PIC18LF66K80T-I/MR
PIC24EP512GP206-E/MR
PIC24EP512GP206-H/MR
PIC24EP512GP206-I/MR
PIC24EP512GP206T-E/MR
PIC24EP512GP206T-H/MR
PIC24EP512GP206T-I/MR
PIC24EP512GP806-E/MR
PIC24EP512GP806-I/MR
PIC24EP512GP806T-E/MR
PIC24EP512GP806T-I/MR
PIC24EP512MC206-E/MR
PIC24EP512MC206-H/MR
PIC24EP512MC206-I/MR
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PIC24EP512MC206T-H/MR
PIC24EP512MC206T-I/MR
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PIC24FJ1024GA606T-I/MR
PIC24FJ1024GB606-I/MR
PIC24FJ1024GB606T-I/MR
PIC24FJ128DA106-I/MR
PIC24FJ128DA206-I/MR
PIC24FJ128GA006-I/MR
PIC24FJ128GA106-E/MR
PIC24FJ128GA106-I/MR
PIC24FJ128GA106T-I/MR
PIC24FJ128GA306-I/MR
PIC24FJ128GA306T-I/MR
PIC24FJ128GA406-I/MR
PIC24FJ128GA406T-I/MR
PIC24FJ128GA606-I/MR
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PIC24FJ128GB206-I/MR
PIC24FJ128GB406-I/MR
PIC24FJ128GB406T-I/MR
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PIC24FJ192GA106-I/MR
PIC24FJ192GB106-I/MR
PIC24FJ256DA106-I/MR
PIC24FJ256DA206-I/MR
PIC24FJ256GA106-E/MR
PIC24FJ256GA106-I/MR
PIC24FJ256GA106T-E/MR
PIC24FJ256GA106T-I/MR
PIC24FJ256GA406-I/MR
PIC24FJ256GA406T-I/MR
PIC24FJ256GA606-I/MR
PIC24FJ256GA606T-I/MR
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PIC24FJ256GB106T-I/MR
PIC24FJ256GB206-I/MR
PIC24FJ256GB206T-I/MR
PIC24FJ256GB406-I/MR
PIC24FJ256GB406T-I/MR
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PIC24FJ256GB606T-I/MR
PIC24FJ512GA606-I/MR
PIC24FJ512GA606T-I/MR
PIC24FJ512GB606-I/MR
PIC24FJ512GB606T-I/MR
PIC24FJ64GA006-I/MR
PIC24FJ64GA006T-I/MR
PIC24FJ64GA106-E/MR
PIC24FJ64GA106-I/MR
PIC24FJ64GA106T-I/MR
PIC24FJ64GA106T-I/MR029
PIC24FJ64GA106T-I/MR032
PIC24FJ64GA106T-I/MR033
PIC24FJ64GA106T-I/MR035
PIC24FJ64GA306-I/MR
PIC24FJ64GA306T-I/MR
PIC24FJ64GA306T-I/MR024
PIC24FJ64GA406-I/MR
PIC24FJ64GA406T-I/MR
PIC24FJ64GB106-I/MR
PIC24FJ64GB406-I/MR
PIC24FJ64GB406T-I/MR
PIC24FJ64GC006-I/MR
PIC24FJ96GA006-I/MR

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PIC24HJ128GP206A-E/MR
PIC24HJ128GP206A-I/MR
PIC24HJ128GP206AT-E/MR
PIC24HJ128GP206AT-I/MR
PIC24HJ128GP306A-E/MR
PIC24HJ128GP306A-I/MR
PIC24HJ128GP306AT-E/MR
PIC24HJ128GP306AT-I/MR
PIC24HJ128GP506A-E/MR
PIC24HJ128GP506A-H/MR
PIC24HJ128GP506A-I/MR
PIC24HJ128GP506AT-E/MR
PIC24HJ128GP506AT-H/MR
PIC24HJ128GP506AT-I/MR
PIC24HJ256GP206A-E/MR
PIC24HJ256GP206A-I/MR
PIC24HJ256GP206AT-E/MR
PIC24HJ256GP206AT-I/MR
PIC24HJ64GP206A-E/MR
PIC24HJ64GP206A-I/MR
PIC24HJ64GP206A-I/MR031
PIC24HJ64GP206A-I/MRA28
PIC24HJ64GP206AT-E/MR
PIC24HJ64GP206AT-I/MR
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PIC24HJ64GP206AT-I/MRA28
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PIC24HJ64GP506A-I/MR
PIC24HJ64GP506AT-E/MR
PIC24HJ64GP506AT-I/MR
PIC32MK0512GPD064-E/MR
PIC32MK0512GPD064-I/MR
PIC32MK0512GPD064T-E/MR
PIC32MK0512GPD064T-I/MR
PIC32MK0512GPE064-E/MR
PIC32MK0512GPE064-I/MR
PIC32MK0512GPE064T-E/MR
PIC32MK0512GPE064T-I/MR
PIC32MK0512MCF064-E/MR
PIC32MK0512MCF064-I/MR
PIC32MK0512MCF064T-E/MR
PIC32MK0512MCF064T-I/MR
PIC32MK1024GPD064-E/MR
PIC32MK1024GPD064-I/MR

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PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MK1024GPD064T-E/MR
PIC32MK1024GPD064T-I/MR
PIC32MK1024GPE064-E/MR
PIC32MK1024GPE064-I/MR
PIC32MK1024GPE064T-E/MR
PIC32MK1024GPE064T-I/MR
PIC32MK1024MCF064-E/MR
PIC32MK1024MCF064-I/MR
PIC32MK1024MCF064T-E/MR
PIC32MK1024MCF064T-I/MR
PIC32MX120F064H-50I/MR
PIC32MX120F064H-I/MR
PIC32MX120F064HT-50I/MR
PIC32MX120F064HT-I/MR
PIC32MX120F064HT-V/MR
PIC32MX120F064H-V/MR
PIC32MX130F128H-50I/MR
PIC32MX130F128H-I/MR
PIC32MX130F128HT-50I/MR
PIC32MX130F128HT-I/MR
PIC32MX130F128HT-V/MR
PIC32MX130F128H-V/MR
PIC32MX150F256H-50I/MR
PIC32MX150F256H-I/MR
PIC32MX150F256HT-50I/MR
PIC32MX150F256HT-I/MR
PIC32MX150F256HT-V/MR
PIC32MX150F256H-V/MR
PIC32MX170F512H-50I/MR
PIC32MX170F512H-I/MR
PIC32MX170F512HT-50I/MR
PIC32MX170F512HT-I/MR
PIC32MX170F512HT-V/MR
PIC32MX170F512H-V/MR
PIC32MX230F128H-50I/MR
PIC32MX230F128H-I/MR
PIC32MX230F128HT-50I/MR
PIC32MX230F128HT-I/MR
PIC32MX230F128HT-V/MR
PIC32MX230F128H-V/MR
PIC32MX250F256H-50I/MR
PIC32MX250F256H-50I/MR/J21
PIC32MX250F256H-I/MR
PIC32MX250F256HT-50I/MR

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Affected Catalog Part Number

PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MX250F256HT-50I/MRJ21
PIC32MX250F256HT-I/MR
PIC32MX250F256HT-V/MR
PIC32MX250F256H-V/MR
PIC32MX270F512H-50I/MR
PIC32MX270F512H-I/MR
PIC32MX270F512HT-50I/MR
PIC32MX270F512HT-I/MR
PIC32MX270F512HT-V/MR
PIC32MX270F512H-V/MR
PIC32MX320F032H-40I/MR
PIC32MX320F032H-40V/MR
PIC32MX320F032HT-40I/MR
PIC32MX320F032HT-40V/MR
PIC32MX320F064H-40I/MR
PIC32MX320F064H-40V/MR
PIC32MX320F064H-80I/MR
PIC32MX320F064H-80V/MR
PIC32MX320F064HT-40I/MR
PIC32MX320F064HT-40V/MR
PIC32MX320F064HT-80I/MR
PIC32MX320F064HT-80V/MR
PIC32MX320F128H-80I/MR
PIC32MX320F128H-80V/MR
PIC32MX320F128HT-80I/MR
PIC32MX320F128HT-80V/MR
PIC32MX340F128H-80I/MR
PIC32MX340F128H-80V/MR
PIC32MX340F128HT-80I/MR
PIC32MX340F128HT-80V/MR
PIC32MX340F256H-80I/MR
PIC32MX340F256H-80I/MR022
PIC32MX340F256H-80V/MR
PIC32MX340F256HT-80I/MR
PIC32MX340F256HT-80I/MR022
PIC32MX340F256HT-80V/MR
PIC32MX340F512H-80I/MR
PIC32MX340F512H-80V/MR
PIC32MX340F512HT-80I/MR
PIC32MX340F512HT-80V/MR
PIC32MX350F128H-I/MR
PIC32MX350F128HT-I/MR
PIC32MX350F128HT-V/MR
PIC32MX350F128H-V/MR

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Affected Catalog Part Number

PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MX350F256H-I/MR
PIC32MX350F256HT-I/MR
PIC32MX350F256HT-V/MR
PIC32MX350F256H-V/MR
PIC32MX370F512H-I/MR
PIC32MX370F512HT-I/MR
PIC32MX370F512HT-V/MR
PIC32MX370F512H-V/MR
PIC32MX420F032H-40I/MR
PIC32MX420F032H-40V/MR
PIC32MX420F032HT-40I/MR
PIC32MX420F032HT-40V/MR
PIC32MX440F128H-80I/MR
PIC32MX440F128H-80V/MR
PIC32MX440F128HT-80I/MR
PIC32MX440F128HT-80V/MR
PIC32MX440F256H-80I/MR
PIC32MX440F256H-80V/MR
PIC32MX440F256HT-80I/MR
PIC32MX440F256HT-80V/MR
PIC32MX440F512H-80I/MR
PIC32MX440F512H-80V/MR
PIC32MX440F512HT-80I/MR
PIC32MX440F512HT-80V/MR
PIC32MX450F128H-I/MR
PIC32MX450F128HT-I/MR
PIC32MX450F128HT-V/MR
PIC32MX450F128H-V/MR
PIC32MX450F256H-120/MR
PIC32MX450F256H-I/MR
PIC32MX450F256HT-120/MR
PIC32MX450F256HT-I/MR
PIC32MX450F256HT-V/MR
PIC32MX450F256H-V/MR
PIC32MX470F512H-120/MR
PIC32MX470F512H-I/MR
PIC32MX470F512HT-120/MR
PIC32MX470F512HT-I/MR
PIC32MX470F512HT-V/MR
PIC32MX470F512H-V/MR
PIC32MX530F128H-50I/MR
PIC32MX530F128H-I/MR
PIC32MX530F128HT-50I/MR
PIC32MX530F128HT-I/MR

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Affected Catalog Part Number

PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MX530F128HT-V/MR
PIC32MX530F128H-V/MR
PIC32MX534F064H-I/MR
PIC32MX534F064HT-I/MR
PIC32MX534F064HT-V/MR
PIC32MX534F064H-V/MR
PIC32MX550F256H-50I/MR
PIC32MX550F256H-I/MR
PIC32MX550F256HT-50I/MR
PIC32MX550F256HT-I/MR
PIC32MX550F256HT-V/MR
PIC32MX550F256H-V/MR
PIC32MX564F064H-I/MR
PIC32MX564F064HT-I/MR
PIC32MX564F064HT-V/MR
PIC32MX564F064H-V/MR
PIC32MX564F128H-I/MR
PIC32MX564F128HT-I/MR
PIC32MX564F128HT-I/MRC21
PIC32MX564F128HT-V/MR
PIC32MX564F128H-V/MR
PIC32MX570F512H-50I/MR
PIC32MX570F512H-I/MR
PIC32MX570F512HT-50I/MR
PIC32MX570F512HT-I/MR
PIC32MX570F512HT-V/MR
PIC32MX570F512H-V/MR
PIC32MX575F256H-80I/MR
PIC32MX575F256H-80V/MR
PIC32MX575F256HT-80I/MR
PIC32MX575F256HT-80V/MR
PIC32MX575F512H-80I/MR
PIC32MX575F512H-80V/MR
PIC32MX575F512HT-80I/MR
PIC32MX575F512HT-80V/MR
PIC32MX664F064H-I/MR
PIC32MX664F064HT-I/MR
PIC32MX664F064HT-V/MR
PIC32MX664F064H-V/MR
PIC32MX664F128H-I/MR
PIC32MX664F128HT-I/MR
PIC32MX664F128HT-V/MR
PIC32MX664F128H-V/MR
PIC32MX675F256H-80I/MR

Affected Catalog Part Number

PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MX675F256H-80V/MR
PIC32MX675F256HT-80I/MR
PIC32MX675F256HT-80V/MR
PIC32MX675F512H-80I/MR
PIC32MX675F512H-80V/MR
PIC32MX675F512HT-80I/MR
PIC32MX675F512HT-80V/MR
PIC32MX695F512H-80I/MR
PIC32MX695F512H-80I/MRD21
PIC32MX695F512H-80V/MR
PIC32MX695F512HT-80I/MR
PIC32MX695F512HT-80I/MRD21
PIC32MX695F512HT-80V/MR
PIC32MX764F128H-I/MR
PIC32MX764F128HT-I/MR
PIC32MX764F128HT-V/MR
PIC32MX764F128H-V/MR
PIC32MX775F256H-80I/MR
PIC32MX775F256H-80V/MR
PIC32MX775F256HT-80I/MR
PIC32MX775F256HT-80V/MR
PIC32MX775F512H-80I/MR
PIC32MX775F512H-80I/MRE21
PIC32MX775F512H-80V/MR
PIC32MX775F512HT-80I/MR
PIC32MX775F512HT-80V/MR
PIC32MX795F512H-80I/MR
PIC32MX795F512H-80V/MR
PIC32MX795F512HT-80I/MR
PIC32MX795F512HT-80V/MR
PIC32MZ0512EFE064-E/MR
PIC32MZ0512EFE064-E/MRA21
PIC32MZ0512EFE064-I/MR
PIC32MZ0512EFE064T-E/MR
PIC32MZ0512EFE064T-E/MRA21
PIC32MZ0512EFE064T-I/MR
PIC32MZ0512EFF064-E/MR
PIC32MZ0512EFF064-I/MR
PIC32MZ0512EFF064T-E/MR
PIC32MZ0512EFF064T-I/MR
PIC32MZ0512EFK064-E/MR
PIC32MZ0512EFK064-I/MR
PIC32MZ0512EFK064T-E/MR
PIC32MZ0512EFK064T-I/MR

Affected Catalog Part Number

PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MZ1024ECG064-I/MR
PIC32MZ1024ECG064-I/MRDD9
PIC32MZ1024ECG064T-I/MR
PIC32MZ1024ECG064T-I/MRDD9
PIC32MZ1024ECH064-I/MR
PIC32MZ1024ECH064T-I/MR
PIC32MZ1024ECM064-I/MR
PIC32MZ1024ECM064T-I/MR
PIC32MZ1024EFE064-E/MR
PIC32MZ1024EFE064-I/MR
PIC32MZ1024EFE064T-E/MR
PIC32MZ1024EFE064T-I/MR
PIC32MZ1024EFF064-E/MR
PIC32MZ1024EFF064-I/MR
PIC32MZ1024EFF064T-E/MR
PIC32MZ1024EFF064T-I/MR
PIC32MZ1024EFG064-E/MR
PIC32MZ1024EFG064-I/MR
PIC32MZ1024EFG064T-E/MR
PIC32MZ1024EFG064T-I/MR
PIC32MZ1024EFH064-E/MR
PIC32MZ1024EFH064-I/MR
PIC32MZ1024EFH064T-E/MR
PIC32MZ1024EFH064T-I/MR
PIC32MZ1024EFK064-E/MR
PIC32MZ1024EFK064-I/MR
PIC32MZ1024EFK064T-E/MR
PIC32MZ1024EFK064T-I/MR
PIC32MZ1024EFM064-E/MR
PIC32MZ1024EFM064-I/MR
PIC32MZ1024EFM064T-E/MR
PIC32MZ1024EFM064T-I/MR
PIC32MZ2048ECG064-I/MR
PIC32MZ2048ECG064T-I/MR
PIC32MZ2048ECH064-I/MR
PIC32MZ2048ECH064-I/MREE9
PIC32MZ2048ECH064T-I/MR
PIC32MZ2048ECH064T-I/MREE9
PIC32MZ2048ECM064-I/MR
PIC32MZ2048ECM064T-I/MR
PIC32MZ2048EFG064-E/MR
PIC32MZ2048EFG064-I/MR
PIC32MZ2048EFG064T-E/MR
PIC32MZ2048EFG064T-I/MR

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PCN_LIAL-17KNYR589
CATALOG_PART_NBR
PIC32MZ2048EFH064-250I/MR
PIC32MZ2048EFH064-E/MR
PIC32MZ2048EFH064-I/MR
PIC32MZ2048EFH064T-250I/MR
PIC32MZ2048EFH064T-E/MR
PIC32MZ2048EFH064T-I/MR
PIC32MZ2048EFM064-E/MR
PIC32MZ2048EFM064-I/MR
PIC32MZ2048EFM064T-E/MR
PIC32MZ2048EFM064T-I/MR